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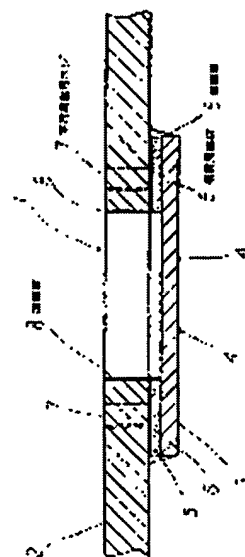
(54) PROBE CARD

(57)Abstract:

PURPOSE: To reduce the contact pressure of a wafer chip to a pad thereby preventing the pad from being damaged by providing, in place of a contact needle, a bump having a circuit printed on a transparent plate.

CONSTITUTION: Bumps 4, 4 are pressed in contact with a pad of a wafer chip from above. At this time, the grounding state is monitored through a transparent plate 3 from a central hole 1 of a card substrate 2. If the pad and bumps 4, 4 are not in uniform contact with each other, they are adjusted by parallel adjusting screws 7, 7.

After the pad and bumps 4, 4 are adjusted in uniform contact visually, a high frequency wave is applied to a vibrating plate 8, causing vibration of the plate. Then, electric characteristic test is conducted. The vibration of the plate 8 is transmitted to the transparent plate 3 itself, and the bumps 4, 4 are eventually vibrated. Since an oxide film formed on the pad is slightly delaminated by the vibration of the bumps 4, 4, conductive property is enhanced, enabling favorable electric characteristic test.



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